

# SQXシリーズ “高純度石英薄膜クロス”

SQX series “High purity thin quartz fabric”

## 超薄膜クロス可能 (10 $\mu$ m以下)

Enable ultrathin fabric (under 10 $\mu$ m)

## 耐熱性 (軟化点 1,600 $^{\circ}$ C)

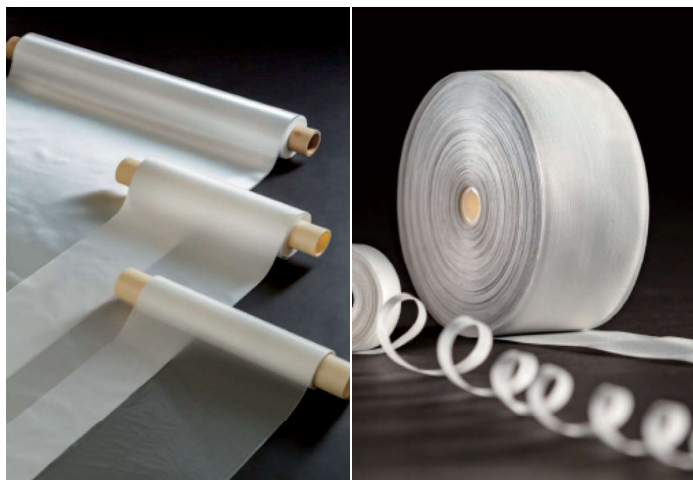
Heat-resistance (softening point 1,600 $^{\circ}$ C)

## 低線膨張

Low CTE (coefficient of thermal expansion)

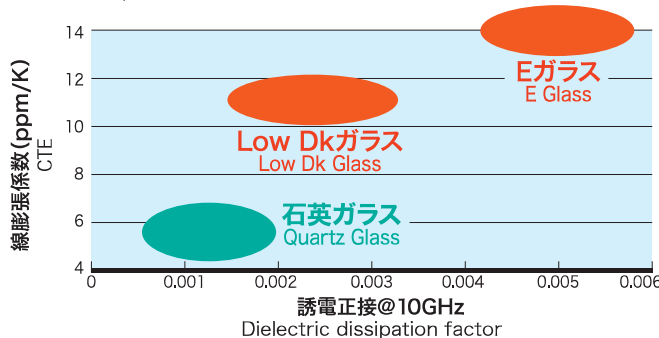
## 低 $\alpha$ 線 (U, Th)

Low  $\alpha$  (U, Th)



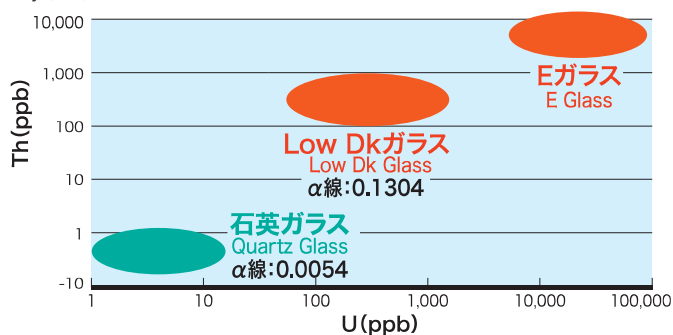
### 各基板の誘電正接、線膨張係数

Dielectric dissipation factor, CTE at each substrate material



### 各基板の $\alpha$ 線、Th量、U量

rays, Th, U content at each substrate material



# SLKシリーズ “低誘電 熱硬化性ポリマー”

SLK series “Low dielectric thermosetting polymer”

## 高接着、低吸水性、フレキシブル(低応力)かつ高耐熱

Good adhesion, Low moisture absorption, flexible (low stress), high heat-resistance

## 誘電率 2.5以下、誘電正接 0.0025以下 (10~80GHz)

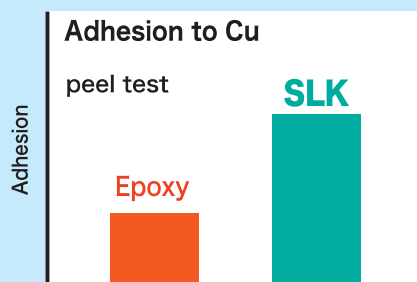
Dielectric constant: less than 2.5, Dielectric dissipation factor: less than 0.0025

### ご使用方法: 封止材、接着剤、コーティング材設計可能

Application: encapsulation material, adhesive material, enable for tuning the coating material design

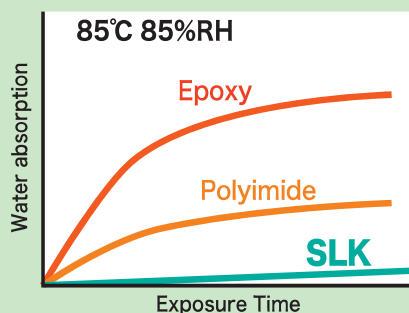
#### 高接着

Good adhesion to Cu, others



#### 低吸水性

Low moisture absorption



#### フレキシブル(低弾性)

Flexible

Lower than 100MPa

#### 高耐熱(高分解温度)

Good heat-resistance (decomposition temperature)

more than 400 $^{\circ}$ C